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DONALD C. ABBOTT ET AL.

e Application of

Serial No. 10/724,498 (TI-28098.1)

Filed: December 1, 2003

For: SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING PLATED LEADFRAME INCLUDING GOLD SELECTIVELY COVERING AREAS TO BE SOLDERED

Art Unit 2814

Examiner Wael M. Fahmy

Customer No. 23494

Director of the United States Patent and Trademark Office P. O. Box 1450 Alexandria, VA 22313-1450 **CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37 CFR 1.8**

I hereby certify that the attached document is being deposited with the United States Postal Service with sufficient postage for First Class Mail in an envelope addressed to Director of the United States Patent and Trademark Office, P.O. Box 1450,, Alexandria, VA 22313-1450 or is being facsimile transmitted on the date indicated below:

Jav M. Cantor, Reg. No. 19,906

AMENDMENT UNDER 37 C.F.R. 1.111

Dear Sir:

In response to the Office action dated June 1, 2005, please amend the above-identified application as follows: